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Chair, ISSM Organizing Committee
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Ayako Shimazaki
Chairman, ISSM Steering Committee
Toshiba Nanoanalysis Corporation

Sponsorship for the 30th International Symposium on Semiconductor Manufacturing (ISSM2024)

We would like to take this opportunity to express our sincere appreciation for your continued support of the ISSM (International Symposium on Semiconductor Manufacturing).

Since its inauguration in 1992, ISSM has been recognized as one of the most important international conferences on semiconductor production technology and has established its position as a major conference in the field of semiconductor production.

Recently, semiconductor manufacturing technology, the theme of ISSM, has been shifting more and more from "manufacturing technology" to "usage technology". At a time when it is necessary to evaluate and select technologies based on a broad view of semiconductor manufacturing technology as a whole, ISSM will make further contributions to the development of semiconductor manufacturing as the only international conference that can evaluate systemic approaches that integrate different technological fields, taking advantage of its characteristics of covering all semiconductor manufacturing technologies. In addition to the technological aspect, new changes are also permeating the geographical raw material procurement and reuse issues on the SCM axis, as well as the issues of responding to production technologies in accordance with a decarbonized world from end users.

The 30th ISSM2024 will be held on December 9-10, 2024, at KFC Hall (Ryogoku, Tokyo) to promote beneficial collaboration among the semiconductor industry to address new challenges in semiconductor production technology, thereby contributing to a new leap forward for the semiconductor industry and its lasting development and prosperity.

We would like to ask for your kind support for ISSM2024 as sponsors.

Sincerely yours

Outline of ISSM 2024

1. Conference Name: The 30th International Symposium on Semiconductor Manufacturing 2024 (ISSM2024)
2. Sponsor
 - Co-sponsored by:
 - IEEE Electron Devices Society
 - Minimal Fab
 - Semiconductor Equipment Association of Japan (SEAJ)
 - Semiconductor Equipment and Materials International (SEMI)
 - Taiwan Semiconductor Industry Association (TSIA)
 - Endorsement by:
 - The Japan Society of Applied Physics
3. Date: Monday, December 9 and Tuesday, December 10, 2024
4. Venue: KFC(Kokusai Fashion Center) Hall
 - 1-6-1 Yokoami Sumida-ku,Tokyo 130-0015 Japan
 - +81-3-5610-5810
 - <https://issm.semiconportal.net/venue/>
5. Program
 - ISSM2024 plans to include:
 - Keynote speeches
 - Tutorial sessions
 - Highlighted sessions
 - Oral presentation by selected authors
 - Poster presentation by selected authors
6. Conference Highlight Theme
 - IoT and AI Solution
 - Leading-edge semiconductor fabs
 - Sustainable Semiconductor Manufacturing and Global Environmental Preservation
 - Next Generation 3D Packaging and Chiplets Integration Technology: New Horizons from Integration to Test
7. Conference Areas
 - Fab Management
 - * Factory Design & Automated Material Handling (FD)
 - * Manufacturing Strategy and Operation Management (MS)
 - * Manufacturing Control and Execution (MC)
 - * Environment, Safety and Health (ES)
 - * Intelligent Data Management (ID)
 - Process Integration
 - * Process and Material Optimization (PO)
 - * Yield Enhancement Methodology (YE)
 - * Contamination Control and Ultraclean Technology (UC)
 - * Process Control and Monitoring (PC)
 - * Process and Metrology Equipment (PE)
 - * Design for Manufacturing (DM)
 - * Manufacturing Technology for Variety Devices (VD)
 - Final Manufacturing
 - * 3D Chiplet & Packaging (TP)
8. Expected participants: 250
9. Conference official language: English

ISSM 2024 Sponsorship Selection and Benefit

Level	Platinum	Gold	Silver	Bronze	Reception	Lanyard
Maximum number of sponsors	—	—	—	—	2	1
Sponsorship fee (10% tax to be added)	¥800,000	¥600,000	¥400,000	¥200,000	¥400,000	¥200,000
Participation to ISSM 2024						
Free tickets to ISSM 2024	6	4	2	1	1	1
Visibility						
Logo on ISSM2024 website	Yes	Yes	Yes	Yes	Yes	Yes
1-min PR movie prior to keynote speech	Yes	Yes				
Logo appeared on online proceedings	Yes	Yes	Yes	Yes	Yes	Yes
Logo appeared on interval screen	Yes	Yes	Yes	Yes	Yes	Yes
Logo on sponsorship banner at the venue	Yes	Yes	Yes	Yes	Yes	Yes
Logo at reception hall					Yes	
Speech at reception					Yes	
Company name on lanyard						Yes
Exhibition						
Exhibit Booth	Yes	Yes	Yes	Yes		

Application deadline: October 31, 2024

■ Contact

ISSM 2024 Secretariat

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